【外資系半導体メーカー】半導体プロセス統合エンジニア｜名古屋

300mmウェハ製造｜プロセス開発・歩留まり改善

募集職種

人材紹介会社
モーガン・マッキンリー

求人ID
1621974

業種
銀行・信託銀行・信用金庫

雇用形態
正社員

勤務地
愛知県

給与
経験考慮の上、応相談

更新日
2026年11月11日 21:43

応募必要条件

職務経験
3年以上

キャリアレベル
中途経験者レベル

英語レベル
ビジネス会話レベル

日本語レベル
流暢レベル

最終学歴
大学卒： 学士号

現在のビザ
日本での就労許可が必要です

募集要項

外資系大手半導体グループ傘下の半導体ファウンドリ企業にて、**300mm（12インチ）ウェハ製造におけるプロセス統合**を担うエンジニアを募集しています。

新規半導体製品のプロセス設計・開発から量産立ち上げ、歩留まり改善、品質安定化まで幅広く担当。複数の製造工程を横断しながら、次世代半導体技術の実用化と**安定した量産体制の確立**を技術面からリードします。

世界的な半導体グループの技術基盤のもと、最先端の製造技術とプロセス統合の専門性を深められる環境です。

さらに、年間休日126日、年次有給休暇23日、フレックスタイム制など、働きやすさと専門性の向上を両立できる点も魅力です。

主な職務内容

- **新規製品のプロセス統合・量産立ち上げ：** 新しい半導体製品の開発から量産移行まで、製造工程全体を考慮したプロセス統合手法を設計・実行する。
- **新技術の量産化・プロセス移管：** 顧客の付加価値の高い半導体技術や製造プロセスの移管プロジェクトを支援し、量産化を推進する。
- **製造仕様・設計ルールの策定：** 各工程のプロセス開発チームと連携し、設計ルールや量産に必要な技術仕様を策定する。
- **歩留まり・品質改善：** 製造プロセスの評価・最適化を行い、不良や欠陥の削減、歩留まりの改善、製造品質の安定化を推進する。
- **技術・製造効率の向上：** ファウンドリの技術基盤を活用して新規ビジネス案件の獲得を技術面から支援するとともに、新しい製造プロセスや設備の導入を評価し、生産性・製造効率の向上を図る。

Join a **world-class semiconductor foundry specialising in advanced 300mm wafer fabrication** as a **Semiconductor Process Integration Engineer** in Nagoya, Japan. This permanent opportunity focuses on semiconductor process development, wafer manufacturing optimisation and the successful introduction of new technologies into mass production.

You will play a central role in **semiconductor process integration, process engineering and high-volume manufacturing**, helping ensure that advanced semiconductor products move efficiently from development into stable commercial production.

The position involves designing and executing **process integration methodologies** to support new product development, technology qualification, manufacturing ramp-up and ongoing process stability.

A key responsibility will be collaborating with **unit process development teams** to establish design rules, define technical specifications and ensure that individual manufacturing processes are effectively integrated into complete semiconductor fabrication flows.

You will also lead technical initiatives focused on **wafer yield improvement, defect reduction, process stabilisation and manufacturing quality**, contributing directly to the performance and productivity of large-scale fabrication facilities.

Working closely with internal engineering teams and international foundry customers, you will support **technology transfer and technology porting programmes**, helping bring high-value-added semiconductor technologies into mass production.

Beyond manufacturing process development, you will assess opportunities to improve **fab productivity, equipment utilisation and operational efficiency** through process enhancements and the introduction of new manufacturing equipment.

The role also involves leveraging existing **foundry technology platforms and technical capabilities** to support business development and the acquisition of new commercial programmes.

This opportunity is ideal for engineers with experience in **semiconductor process integration, module process development, wafer fabrication, semiconductor production engineering or yield improvement** who want to deepen their expertise in advanced semiconductor manufacturing.

Key Responsibilities

- Design, develop and execute **semiconductor process integration methodologies** to support new technology development and successful manufacturing ramp-up.
- Coordinate integration activities across **advanced 300mm wafer fabrication processes**.
- Support the introduction of **new semiconductor products and high-value-added technologies** into stable mass production.
- Work closely with **unit process development and module engineering teams** to integrate individual process steps into complete manufacturing flows.
- Define and refine **semiconductor design rules, technical specifications and process integration requirements** for high-volume manufacturing.
- Support international foundry customers through **technology transfer and technology porting programmes**.
- Design, evaluate and optimise **semiconductor fabrication processes** to improve manufacturability and production stability.
- Lead engineering initiatives focused on **wafer yield improvement, defect reduction and manufacturing quality**.
- Investigate process-related technical challenges and implement improvements that enhance **production reliability and process consistency**.
- Evaluate **new process technologies and manufacturing equipment introductions** to improve fab productivity and efficiency.
- Collaborate with **cross-functional engineering and manufacturing teams** to resolve complex integration issues.
- Apply existing **foundry technology platforms and technical assets** to support new business opportunities and commercial programme acquisition.
- Contribute to continuous improvements in **semiconductor manufacturing processes, operational performance and technology readiness**.
- Coordinate technical information and engineering requirements with relevant internal teams and international stakeholders.

スキル・資格

必須条件 経験・資格：

- 工学、理学、または関連分野の高等専門学校（高専）卒業以上

- 半導体製造プロセスの開発や、各製造工程（モジュールプロセス）に関する実務経験
- プロセスインテグレーションや半導体の量産技術・製造技術に関する実務経験

ソフトスキル：
- **主体性・課題解決力：** 複雑なプロセス統合上の課題に対し、主体的に考え、責任を持って解決に取り組めること
- **学習意欲：** 次世代半導体技術や新しい製造プロセスについて、継続的に知識を習得できること
- **部門横断の協働力：** 異なる専門分野のエンジニアと円滑に連携し、共通の目標に向けてプロジェクトを推進できること

語学力：
- **日本語：**流暢
- **英語：**できれば尚可

- **必須ではありませんが、TOEIC 500点以上が望ましいレベル。**技術的なPowerPoint資料の確認・作成、およびグローバル本社や海外顧客とのコミュニケーションができれば歓迎

歓迎条件
- **TOEIC 500点以上**の英語力。技術資料・プレゼンテーション資料の作成や、海外本社・海外顧客との業務調整に対応できる方は歓迎します。
- フラッシュメモリ、不揮発性メモリ、特殊半導体デバイスの製造プロセスに関する経験

採用企業について
世界有数の半導体ファウンドリ企業です。

日本国内に300mm（12インチ）ウェハ対応の先進的な製造拠点を持ち、国際的な半導体グループを背景に、ロジック半導体、組み込み不揮発性メモリ、パワー半導体関連の製造ソリューションを提供しています。

世界各国の主要なテクノロジー企業の半導体開発・製造を支えています。

この求人がおすすめの理由
- **300mmウェハの大規模製造に携われる：** 世界的な半導体グループを背景とするファウンドリ企業で、高度な半導体製造技術に携われます。
- **新規技術の量産化を主導：** 新製品のプロセス開発から量産立ち上げまで、半導体製造の重要な工程を担えます。
- **プロセス統合の専門性を深められる：** 複数の製造工程を横断し、歩留まり改善や品質安定化など、製造技術の中核に携われます。
- **グローバルな技術環境：** 海外本社や海外顧客との連携を通じて、国際的な半導体技術・製造プロジェクトに関われます。
- **年間休日126日・柔軟な働き方：** フレックスタイム制に加え、年間有給休暇23日、長期休暇制度も充実しています。
- **充実した福利厚生：** カフェテリアプラン、確定拠出年金、通勤費全額支給、家族手当・住宅手当などを利用できます。

Required Skills and Qualifications**Experience:**
- **Technical college (KOSEN) graduation or higher** in Engineering, Science or a related technical discipline.
- Practical engineering experience in **semiconductor process development**.
- Hands-on experience working with **module process technology** in semiconductor manufacturing.
- Demonstrated background in **semiconductor process integration**.
- Practical knowledge of **semiconductor production engineering and wafer fabrication processes**.
- Ability to understand and coordinate **technical requirements across multiple semiconductor manufacturing process steps**.
- Experience supporting the development, evaluation or improvement of **semiconductor manufacturing processes**.
- Understanding of **process stability, production quality and engineering problem-solving** within semiconductor fabrication environments.

Soft Skills:
- **Proactive and independent working style**, with the ability to take ownership of complex process integration challenges.
- Strong commitment to **continuous learning and developing expertise in next-generation semiconductor technologies**.
- Excellent **cross-functional collaboration skills** when working with multidisciplinary engineering and manufacturing teams.
- Clear and effective **technical communication skills**.
- Analytical approach to **identifying process issues, evaluating technical options and implementing practical improvements**.
- Strong sense of **responsibility, quality awareness and continuous improvement**.
- Ability to collaborate effectively with **process development, production engineering and manufacturing stakeholders**.

Language Requirements:
- **Japanese:** Fluent proficiency for effective collaboration with domestic engineering and manufacturing teams.
- **English:** Not mandatory as a core qualification, but **TOEIC 500 or above is preferred**, together with the ability to review and prepare technical PowerPoint presentations and communicate with global headquarters and overseas customers.

Preferred Skills & Qualifications
- **English proficiency equivalent to TOEIC 500 or above**, including technical documentation and presentation skills.
- Experience communicating with **global headquarters, international engineering teams or overseas semiconductor customers**.
- Practical experience in **flash memory manufacturing or process development**.
- Knowledge of **non-volatile memory technologies and semiconductor fabrication processes**.
- Experience with **specialised semiconductor device fabrication**.
- Familiarity with **technology transfer, process qualification or manufacturing ramp-up**.
- Experience contributing to **wafer yield improvement, process stabilisation or fab productivity initiatives**.

About the Company

Our client is an established **world-class semiconductor foundry** operating large-scale **300mm wafer fabrication facilities in Japan**.

Backed by a **premier global semiconductor manufacturing group**, the company combines advanced manufacturing capabilities with international technical expertise and an established semiconductor industry network.

Its technology portfolio includes **advanced logic semiconductor technologies, specialised semiconductor devices and integrated foundry solutions**.

The organisation supports **technology innovators around the world**, providing specialised manufacturing capabilities that help bring advanced semiconductor designs into commercial production.

Its engineering teams play an essential role in **semiconductor process development, technology integration, manufacturing optimisation and high-volume production readiness**.

The company emphasises **engineering excellence, stable manufacturing operations and continuous technical improvement**, creating an environment where process engineers can contribute directly to advanced semiconductor production.

Joining this organisation offers the opportunity to work on **complex process integration challenges, new semiconductor technologies and large-scale wafer manufacturing programmes**, while building a long-term career in Japan's semiconductor industry.

Why You'll Love Working Here

- Join a **world-class semiconductor foundry** operating advanced 300mm wafer fabrication facilities.
- Work within an established organisation backed by a **leading global semiconductor manufacturing group**.
- Contribute to **advanced logic semiconductor technologies and specialised device manufacturing**.
- Play an important role in **new technology introduction and semiconductor mass-production ramp-up**.
- Develop expertise in **semiconductor process integration, module process development and wafer fabrication**.
- Lead technical improvements in **wafer yield, defect reduction, process stability and manufacturing quality**.
- Support **technology transfer and technology porting programmes** for international foundry customers.
- Collaborate with **multidisciplinary engineering teams and global technical stakeholders**.
- Gain exposure to **process technology development, equipment introduction and fab productivity improvement**.
- Enjoy an excellent work-life balance with **126 annual holidays**.
- Benefit from **23 days of annual paid leave**.
- Take advantage of **flexible flextime working arrangements**.
- Enjoy **extended seasonal holiday periods**.
- Access a **flexible cafeteria-style employee benefits programme**.
- Benefit from a **Defined Contribution Corporate Pension Plan**.
- Receive **full commuting cost subsidies** in accordance with company policy.
- Take advantage of applicable **family and housing allowances**.
- Build a long-term career in **Japan's advanced semiconductor manufacturing sector** through a permanent position in Nagoya.

会社説明

Morgan McKinleyは国際的な人材コンサルティング会社として、さまざまな業界・分野をリードする採用企業様と、スペシャリストとしてのスキルを有する人材とを結びつけるお手伝いをしています。1988年の創立以来、Morgan McKinleyの名は、「卓越した質のサービス」「市場知識の豊富さ」「No.1企業であり続けようとする強い意志」、そして何よりも「実績」を体現する会社として知られています。

リクルーティング スペシャリストである弊社コンサルタントまでお気軽にお問い合わせください。